

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A heat dissipating structure for an electronic device, comprising:  
a heat source; and  
a heat dissipating member having an inner wall, outer wall, and partition walls,  
wherein the inner wall directly or indirectly receives heat from the heat source,  
wherein the outer wall opposes the inner wall at a distance,  
wherein the partition walls connect the inner wall and the outer wall, the inner wall, outer wall and partition walls define a plurality of through-holes, the through-holes are arranged along at least one of the inner wall and the outer wall, each of the through-holes extends in a vertical direction within a tilt range in which gravitational influence is utilizable, and top and bottom ends of each of the through-holes open to the outside, and  
wherein an optimum distance between opposing inner sides of two adjacent partition walls is set in accordance with a linear function of vertical length of the through-holes, and a distance between the opposing inner sides is set based upon the optimum distance.
2. (Original) The heat dissipating structure according to claim 1, wherein the plurality of through-holes have approximately the same shape, and are lined up along at least one of the inner wall and the outer wall at regular intervals.
3. (Original) The heat dissipating structure according to claim 1, wherein a tilt of each of the through-holes is within 60° to a plumb line.

4. (Original) The heat dissipating structure according to claim 1, wherein a cross-sectional shape of each of the through-holes that is orthogonal to the vertical direction is approximately the same at arbitrary vertical positions.

5. (Canceled)

6. (Currently Amended) The heat dissipating structure according to claim ~~5~~1, wherein assuming the optimum distance between the opposing inner sides is  $w_{opt}$ , the vertical length of the through-hole is  $L$ , and the distance between the opposing inner sides is  $w$ ,  $w_{opt}$  is set according to the following equation  $w_{opt} = 0.01 L + 0.005$  and  $w$  is set within the range of  $0.95 w_{opt} \leq w \leq 1.2 w_{opt}$

7. (Original) The heat dissipating structure according to claim 1, further comprising:  
a heat diffusing member, which is positioned between the heat source and the inner wall of the heat dissipating member, and is in contact with the heat source and an outer side of the inner wall.

8. (Original) The heat dissipating structure according to claim 1, wherein a cross-section that is vertically orthogonal to the through-hole is approximately a square shape, and lengths of four sides of the cross-section of the through-hole are set almost equal.

9. (Original) The heat dissipating structure according to claim 1, wherein the through-

holes are approximately lined up linearly.

10. (Original) The heat dissipating structure according to claim 1, wherein the through-holes are lined up in a circle.

11. (Currently Amended) A heat dissipating structure for an electronic device, comprising:

a heat source;

a heat dissipating member having an inner wall, outer wall, and partition walls, wherein

the inner wall directly or indirectly receives heat from the heat source,

the outer wall opposes the inner wall at a distance,

the partition walls connect the inner wall and the outer wall,

the inner wall, outer wall and partition walls define a plurality of through-holes,

the through-holes are arranged along at least one of the inner wall and the outer wall,

each of the through-holes extending in a vertical direction within a tilt range in

which gravitational influence is utilizable, and top and bottom ends of each of the

through-holes open to the outside; and

~~The heat dissipating structure according to claim 1, further comprising:~~

a case, which houses the heat source and the heat dissipating member,

wherein an outer side of the outer wall of the heat ~~dissipating~~diffusing member is in surface contact with an inner side of the case.

12. (Original) The heat dissipating structure according to claim 1, wherein the inner wall

of the heat dissipating member defines an enclosed space, and the heat source is placed within the enclosed space.

13. (Original) The heat dissipating structure according to claim 1, wherein an outer side of the heat dissipating member has a cooling fin.